

Fig. 1 PRIOR ART

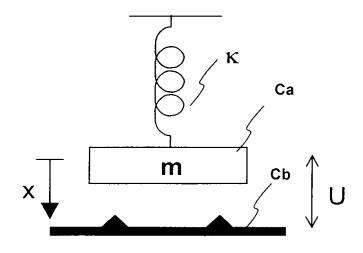
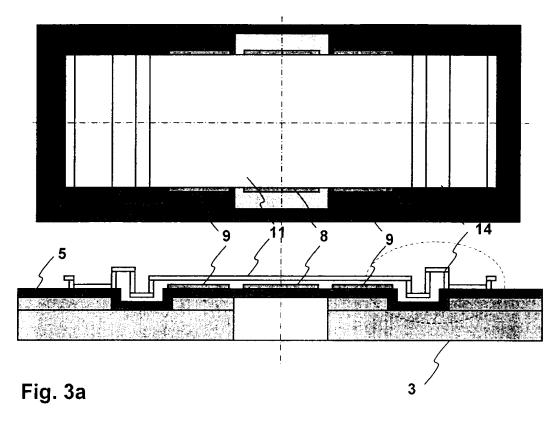
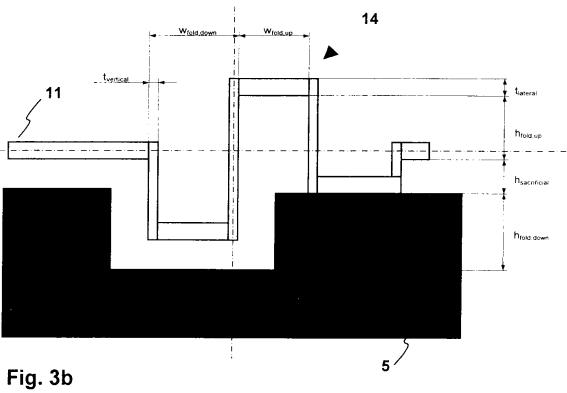


Fig. 2 PRIOR ART





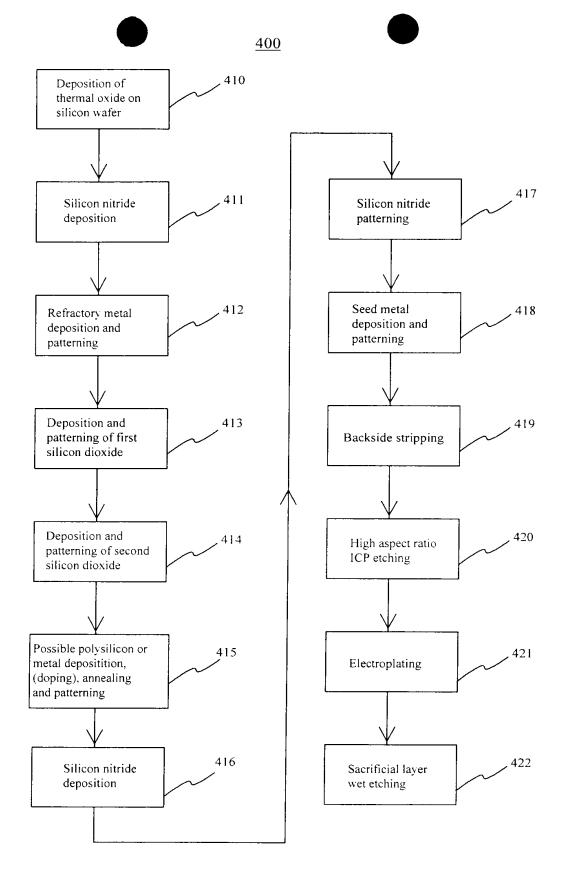
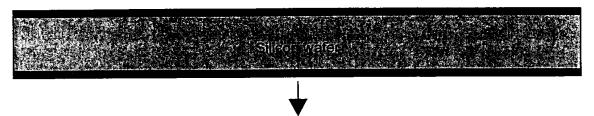
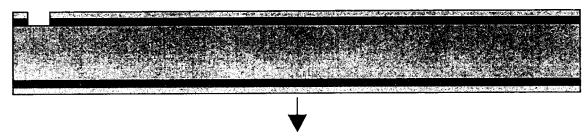


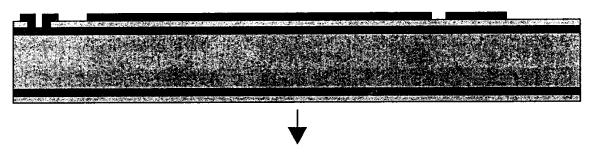
FIG. 4a



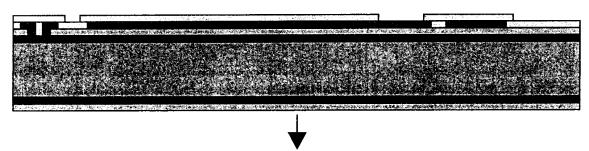
411 Silicon nitride deposition (~1 μ m) and patterning



412 Refractory metal (molybdeen or tungsten) deposition and patterning



413 First silicon dioxide deposition and patterning (plasma) (0.4 - $0.5 \mu m$)



414 Second silicon dioxide deposition and patterning (plasma) ($0.5\,\mu\text{m}$)

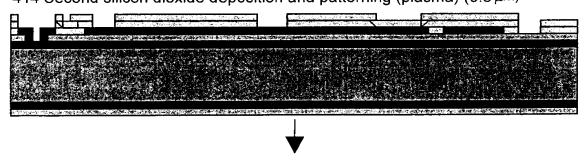
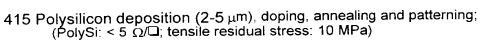
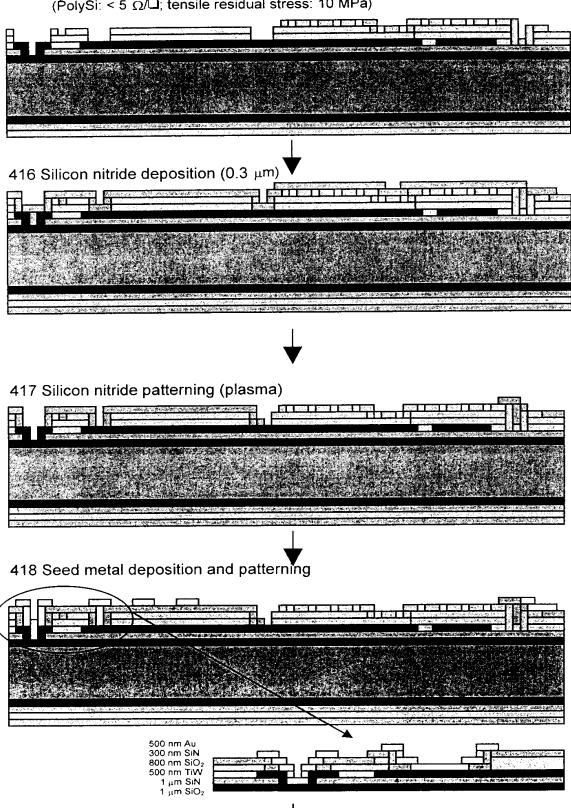


FIG. 4b





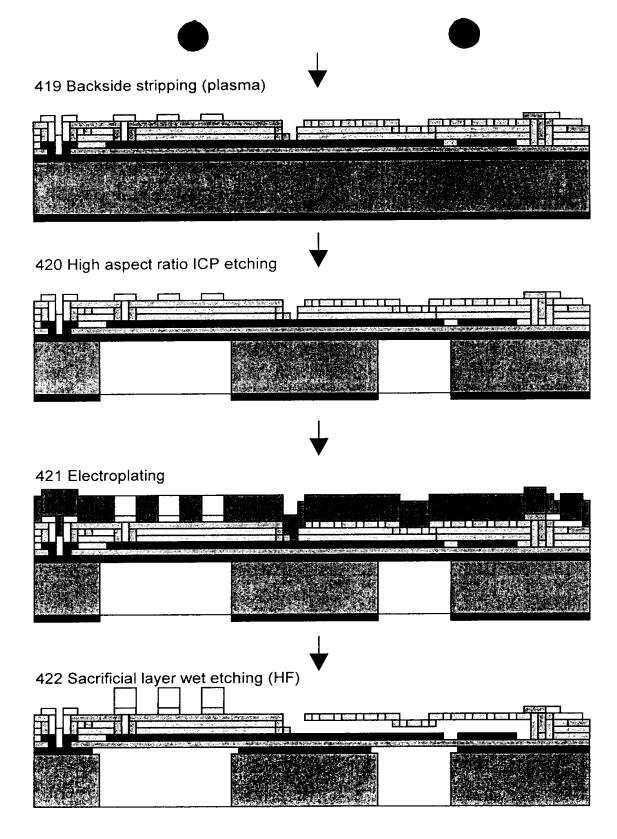


FIG. 4d

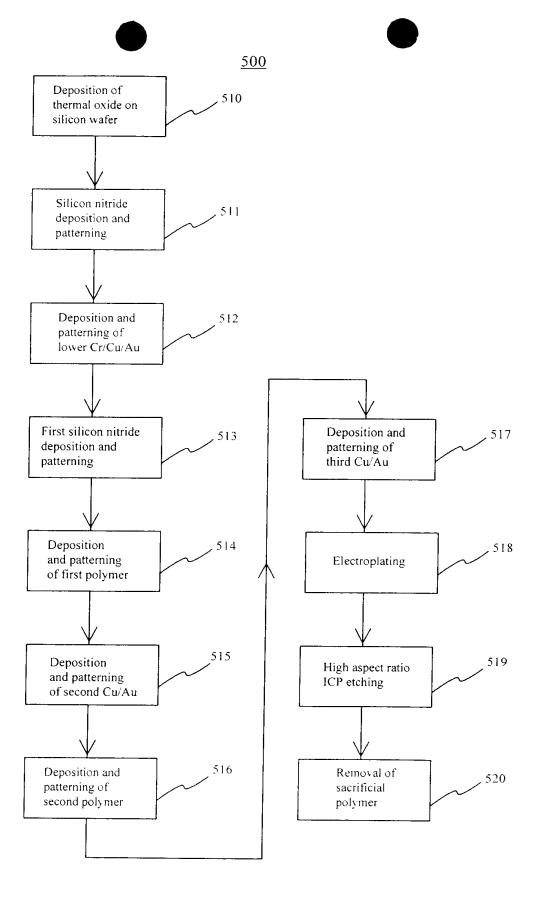


FIG. 5a

510. Thermal oxide (~1 μ m)

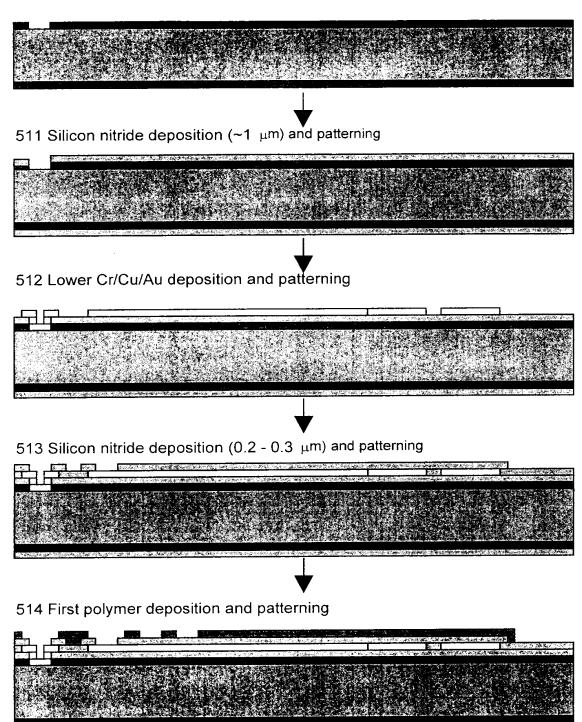
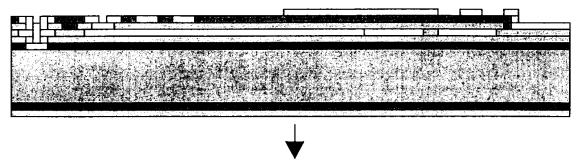


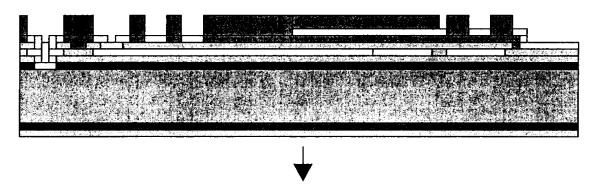
FIG. 5b



515 Second Cu/Au deposition and patterning



516 Second polymer deposition and patterning



517 Third Cu/Au deposition and patterning

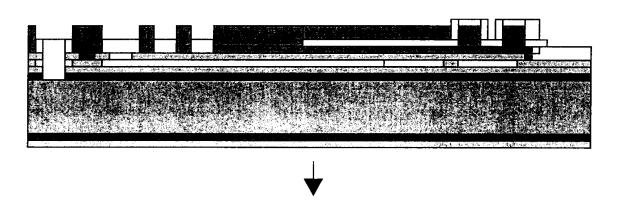


FIG. 5c

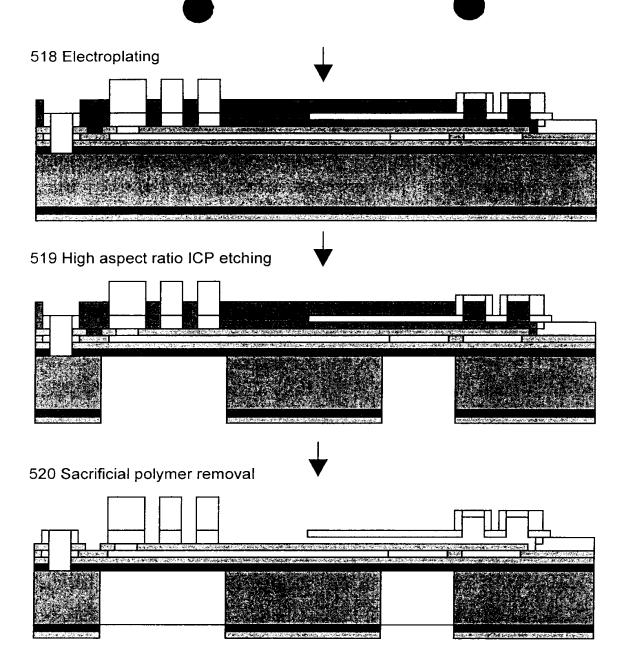


FIG. 5d

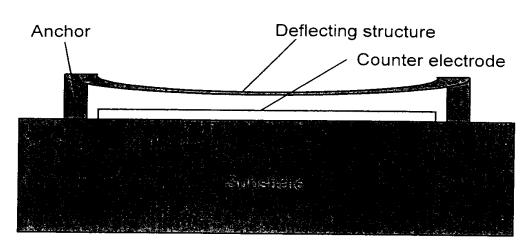


Fig. 6a PRIOR ART

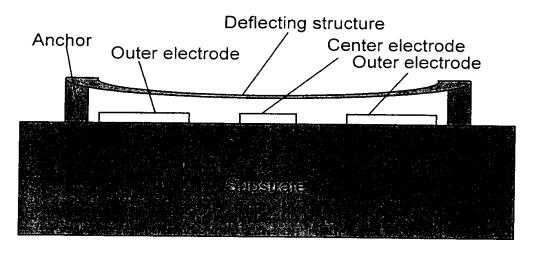


Fig. 6b

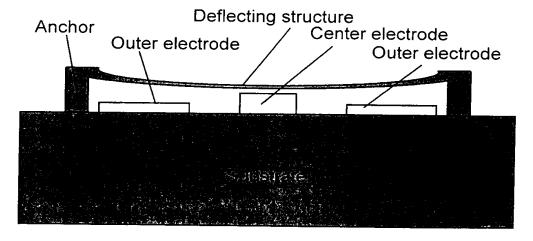


Fig. 6c

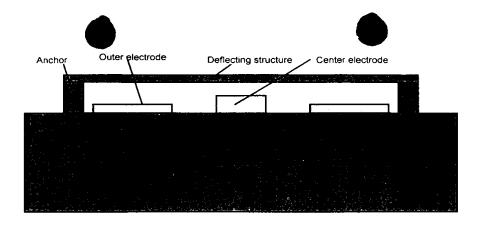


Fig. 7a

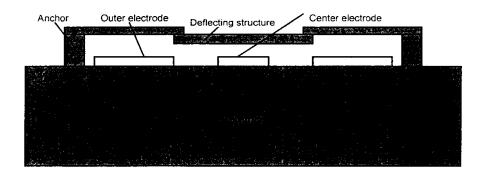


Fig. 7b

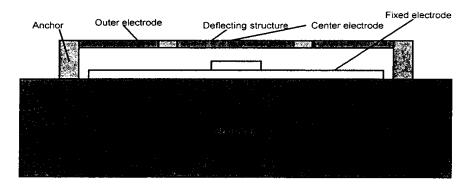


Fig. 7c

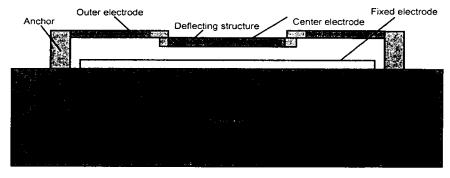
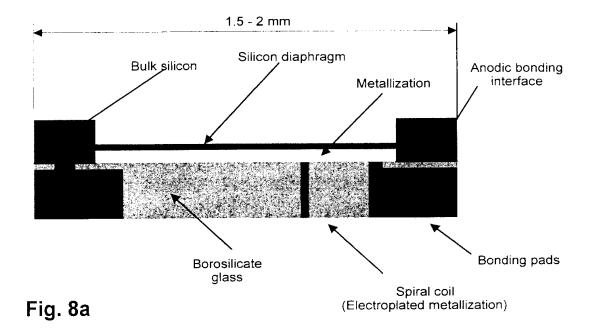


Fig. 7d



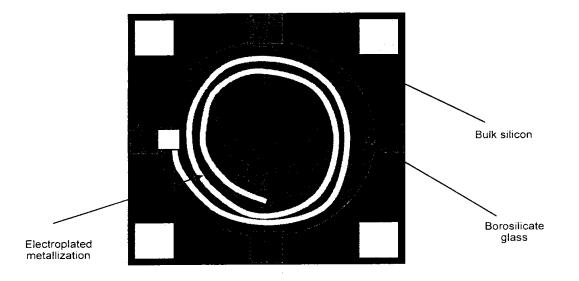


Fig. 8b

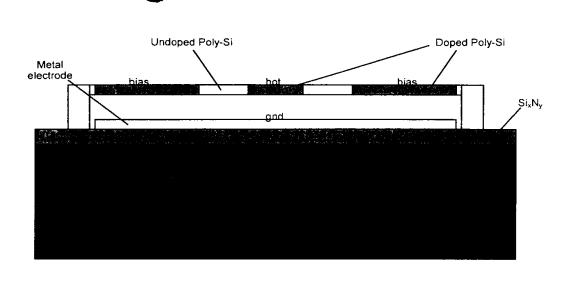


Fig. 9

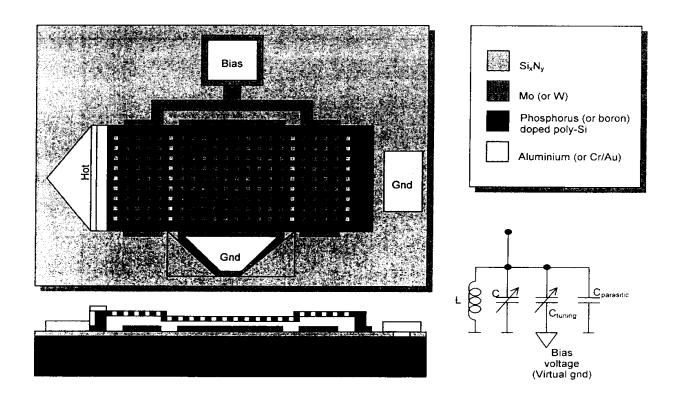
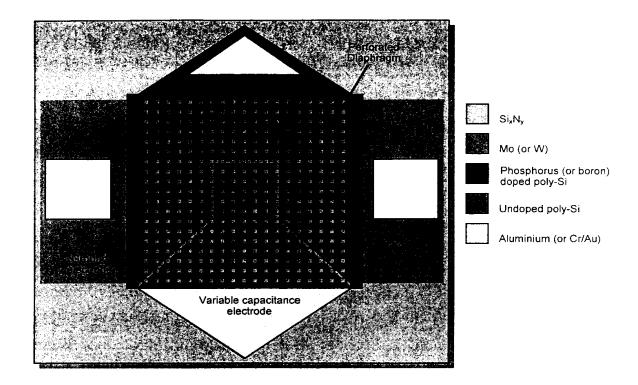


Fig. 10c



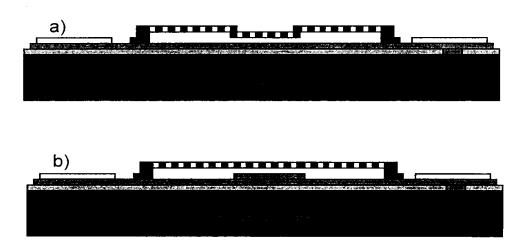


Fig. 10a,b

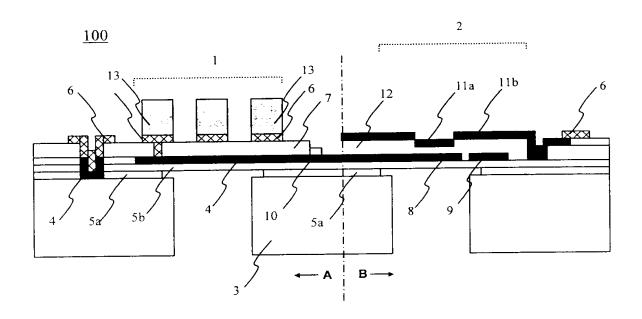


FIG. 11a

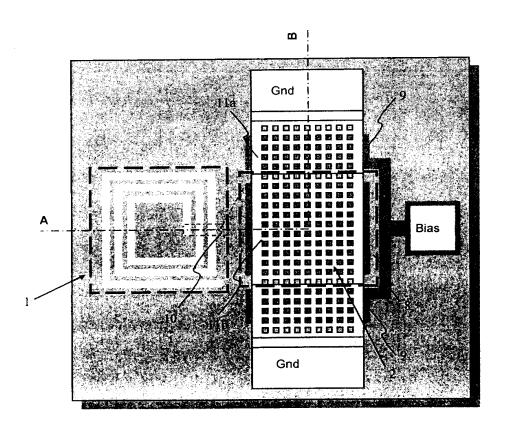


FIG. 11b

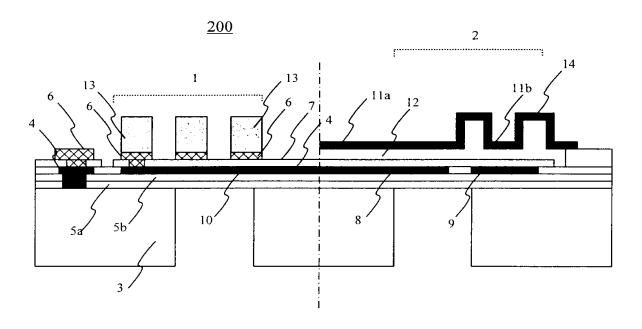


FIG. 12